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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Papathomas *et al.*

Examiner: Berman, S

Serial No.: 09/771,275

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For: **LEAD PROTECTIVE COATING COMPOSITION, PROCESS AND
STRUCTURE THEREOF**

Commissioner for Patents
Washington D.C. 20231

RECEIVED
APR 05 2002
TC 1700

PRELIMINARY AMENDMENT

Sir:

Prior to initial examination on the merits, please amend the above-identified application
as follows:

IN THE CLAIMS

Please amend claims 13, 15 and 20.

Sub D1
13. (TWICE AMENDED) A method for encapsulating a solder joint between an integrated
circuit chip and a substrate, comprising the steps of:
forming a composition that includes a cyanate ester, a photoinitiator, and a coefficient
of thermal expansion reducing dispersed filler;
applying an amount of the composition at a thickness sufficient to cover substantially all
of the solder joint; and
photocuring the composition to reinforce the solder joint.